Microsemi
Power and Microelectronics Group (PMG) – Phoenix Division

Product Change Notification

Date:	**Thursday, January 20, 2011**
PCN#:	**140A00196**
Subject:	**W3H32M64E-XSBX, W3H32M64EA-XSBX, W3H32M72E-XSB2X Die Revision**

Dear Customer,

In an effort to better communicate to you, our user community, we have implemented a e-mail version for our PCN process in addition to our PCN website. While you may receive a notification from us concerning a particular part or part numbers, it is not an indication that you use or have ordered these particular parts, but merely a communication to notify our user community as a whole. Please review your sales orders, POs, records, etc. to determine if this particular PCN impacts your activities or affects your business.

Microsemi Power and Microelectronics Group wishes to inform you of a die revision for the following part numbers: W3H32M64E-XSBX, W3H32M64EA-XSBX, W3H32M72E-XSB2X. The die from Micron will be changing from the U47A to the U67A. Microsemi Phoenix has placed a last time buy on the U47A die to support our customers for the next 3-5 years. If we see that we need to qualify the U67A die, we will inform our customers of the impending die qualification. If you have any questions, please contact the factory.

As technology moves at a much faster pace, advanced embedded electronic components play a more strategic role. Constant changes and advancements in technology mandate that we anticipate changes and directions in technology for the benefit of our customers. As one of the pioneers in advanced semiconductor packaging and high-density memory solutions, we stand ready to assist you in managing this evolution of technology. If we can provide any additional assistance, please contact us at 602.437.1520 or complete a contact form at www.whiteedc.com/contact_us.html.

Best regards,
Microsemi Power and Microelectronics Engineering Group